

A1 voids in the integrated circuit/thermal element interface. By way of example, the microwave energy may have a frequency between 1000 and 300,000 megahertz. It is well known that the microwave range exist between 300,000 MHz and 1,000 MHz. After the thermal epoxy 22 is cured, the encapsulant 26 can be formed into the package with an injection mold process. The solder balls 20 can then be attached to the substrate 14 to complete the assembly. It may be desirable to bake the substrate 14 before curing the thermal epoxy 22 to insure that the curing process does not release water from the substrate material.

Please replace the paragraph beginning at page 7 line 9 with the paragraph below:

A2 Although not shown, an alternate method for assembling the thermal epoxy 22 is contemplated. For this alternate method, the epoxy 22 is applied to the thermal element 24 instead of the integrated circuit 12 before being cured by the microwave generator 28.

#### IN THE CLAIMS

Following is a complete set of claims as amended with this Response. This complete set of claims includes amended claims 10-12, new claims 13-20 and excluding cancelled claims 1-4.

1           5.     A method for assembling an integrated circuit package, comprising:  
2           applying an epoxy to an integrated circuit;  
3           placing a thermal element adjacent to the epoxy; and,  
4           curing the epoxy with energy at a microwave frequency.

1           6.     The method of claim 5, further comprising the step of mounting the integrated  
2     circuit to a substrate.

1           7.     The method of claim 6, further comprising the step of attaching a solder ball  
2     to the substrate.

1           8.     The method of claim 5, further comprising the step of molding an encapsulant  
2     onto the substrate and the integrated circuit.